Product / Process Change Notice

No.: Z200-PCN-DM202108-01-A

Date: August 16, 2021

Change Title : 1Gb (64Mb x16 and 128Mb x8) DDR3/DDR3L technology migration from 38nm to 25nm for industrial / industrial plus products.

Change Classification: ☑ Major ☐ Minor with customer notification ☐ Minor without customer notification
Change item : ☐ DataSheet ☑ Design ☐ Raw Material ☐ Wafer FAB ☐ Assembly ☐ Testing ☐ Packing ☐ Others

Affected Product(s) :

Please refer to Table 1 in details.

Description of Change(s)

Technology migration (38nm to 25nm) for 1Gb DDR3/DDR3L.

Reason for Change(s) :

According to Winbond product roadmap, launch new 1Gb DDR3/DDR3L with 25nm technology.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change (Please refer to attachment I)

Function : No Concern (Compatible between 38nm and 25nm,refer to attachment II)

Reliability : No Concern (Please refer to attachment III)

Hazardous Substances: No Concern (Please refer to attachment IV)

Qualification Plan/ Results :

Base on Winbond EV data result and AG1 reliability report, the new product meets our criteria and no quality concern.

Implementation Plan :

The follow-up disposition of 38nm 64Mb x16 DDR3/DDR3L and 128Mb x8 DDR3/DDR3L :

1) The date of last-buy orders for the 38nm 64Mb x16 and 128Mb x8 DDR3/DDR3L: February 21, 2022.

2) The last shipment date of the 38nm 64Mb x16 and 128Mb x8 DDR3/DDR3L: May 23, 2022.

☐ Date Code: _____ onward ☐ Lot No: _____ onward ☑ Proposed first ship date: November 22, 2021

Originator: (QA)	Hyhuang	***Approval: (QA Dept. Manager)***		***Approval: (QRA Director)***	Chang Shu Cheng

Contact for Questions & Concerns	Name: Betty Huang TEL:886-3-5678168 (ext.76549) FAX: 886-3-5796124 Address : No. 8,Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung City 42881,Taiwan E-mail: Hyhuang8@winbond.com

Customer Comments:

*Note: Please sign this notice, and return to Winbond contact within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.*

Major change: ☐ Approval ☐ Disapproval ☐ Conditional Approval : ____________________.

Minor change with customer notification: ☐ Recognition

Minor change without customer notification: ☐ Approval ☐ Disapproval

☐ Conditional Approval : ____________________

Comment:

Date: ____________________

Dept. name: ____________________

Person in charge: ____________________

Table 1. The affected part no are list below.

W631GG6MB09I	W631GG6MB15I	W631GU6MB12I	W631GG8MB11I	W631GG8MB15J
W631GG6MB09J	W631GG6MB15J	W631GU6MB12J	W631GG8MB11J	W631GU8MB09I
W631GG6MB11I	W631GU6MB09I	W631GU6MB15I	W631GG8MB12I	W631GU8MB11I
W631GG6MB11J	W631GU6MB09J	W631GU6MB15J	W631GG8MB12J	W631GU8MB12I
W631GG6MB12I	W631GU6MB11I	W631GG8MB09I	W631GG8MB15I	W631GU8MB15I
W631GG6MB12J	W631GU6MB11J	W631GG8MB09J		

The comparison table of part no between 38nm and 25nm

Product	38nm Part No	25nm Part No
DDR3 128Mb x8	W631GG8MB	W631GG8NB
DDR3L 128Mb x8	W631GU8MB	W631GU8NB
DDR3 64Mb x16	W631GG6MB	W631GG6NB
DDR3L 64Mb x16	W631GU6MB	W631GU6NB